100 V, 2.0 A, Low V_{CE(sat)} **PNP Transistor**

ON Semiconductor's e²PowerEdge family of low V_{CE(sat)} transistors are miniature surface mount devices featuring ultra low saturation voltage (V_{CE(sat)}) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit	
Collector-Emitter Voltage	V _{CEO}	-100	Vdc	
Collector-Base Voltage	V _{CBO}	-140	Vdc	
Emitter-Base Voltage	V _{EBO}	-7.0	Vdc	
Base Current - Continuous	I _B	1.0	Α	
Collector Current - Continuous	I _C	2.0	Α	
Collector Current - Peak	I _{CM}	3.0	Α	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	800 6.5	mW mW/°C	
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	155	°C/W	
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	2.0 15.6	W mW/°C	
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	64	°C/W	
Junction and Storage Temperature Range	T _J , T _{stg}	−55 to +150	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

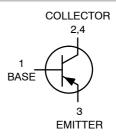
- 1. FR-4 @ 7.6 mm², 1 oz. copper traces. 2. FR-4 @ 645 mm², 1 oz. copper traces.



ON Semiconductor®

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-100 VOLTS, 2.0 AMPS PNP LOW V_{CE(sat)} TRANSISTOR



MARKING DIAGRAM



SOT-223 **CASE 318E** STYLE 1



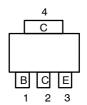
= Assembly Location

= Year

= Work Week

= Specific Device Code = Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

Device	Package	Shipping [†]	
NSS1C200MZ4T1G NSV1C200MZ4T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel	
NSS1C200MZ4T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Collector – Emitter Breakdown Voltage ($I_C = -10 \text{ mAdc}$, $I_B = 0$)	V _{(BR)CEO}	-100			Vdc	
Collector – Base Breakdown Voltage (I _C = -0.1 mAdc, I _E = 0)	V _{(BR)CBO}	-140			Vdc	
Emitter – Base Breakdown Voltage ($I_E = -0.1 \text{ mAdc}, I_C = 0$)	V _{(BR)EBO}	-7.0			Vdc	
Collector Cutoff Current (V _{CB} = -140 Vdc, I _E = 0)	I _{CBO}			-100	nAdc	
Emitter Cutoff Current (V _{EB} = -6.0 Vdc)	I _{EBO}			-50	nAdc	
ON CHARACTERISTICS						
DC Current Gain (Note 3) $ \begin{aligned} &(I_C = -10 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -2.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{aligned} $	h _{FE}	150 120 80 50		360		
Collector – Emitter Saturation Voltage (Note 3) $ \begin{aligned} &(I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A}) \\ &(I_C = -0.5 \text{ A, } I_B = -0.050 \text{ A}) \\ &(I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A}) \\ &(I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A}) \end{aligned} $	V _{CE(sat)}			-0.040 -0.080 -0.125 -0.220	٧	
Base – Emitter Saturation Voltage (Note 3) $(I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A})$	V _{BE(sat)}			-0.950	V	
Base – Emitter Turn–on Voltage (Note 3) (I _C = -1.0 A, V _{CE} = -2.0 V)	V _{BE(on)}			-0.850	V	
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T		120		MHz	
Input Capacitance (V _{EB} = 3.0 V, f = 1.0 MHz)	Cibo		200		pF	
Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	Cobo		22		pF	

^{3.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

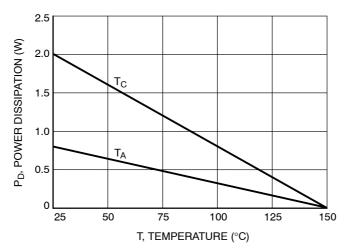


Figure 1. Power Derating

TYPICAL CHARACTERISTICS

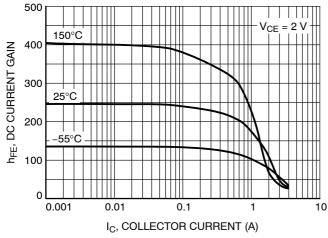


Figure 2. DC Current Gain

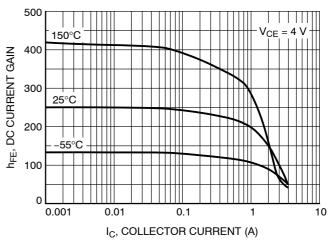


Figure 3. DC Current Gain

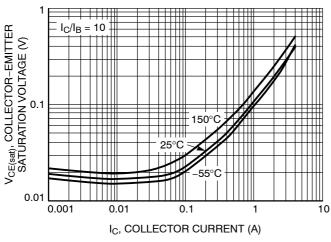


Figure 4. Collector-Emitter Saturation Voltage

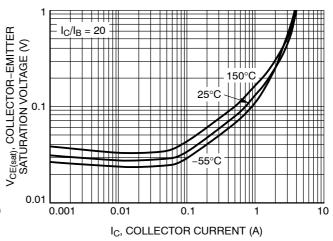


Figure 5. Collector-Emitter Saturation Voltage

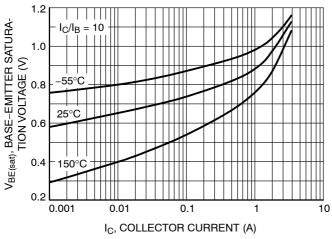


Figure 6. Base-Emitter Saturation Voltage

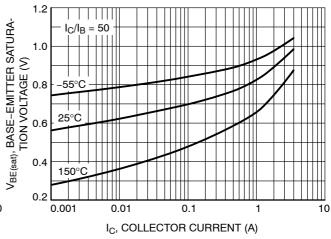
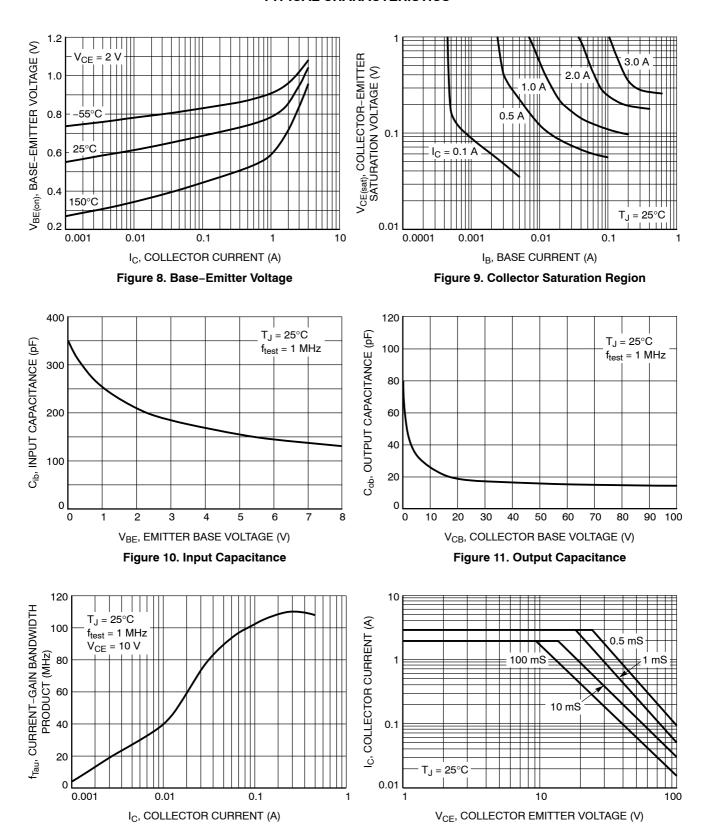


Figure 7. Base-Emitter Saturation Voltage

TYPICAL CHARACTERISTICS



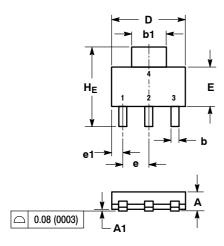
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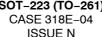
Figure 13. Safe Operating Area

Figure 12. Current-Gain Bandwidth Product

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04





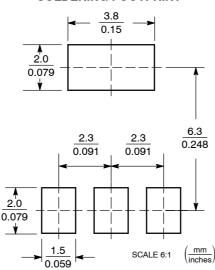
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1: PIN 1. BASE

- 2. COLLECTOR 3. EMITTER
- 4 COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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